

### 描述 / Descriptions

SOD-323 塑封封装 肖特基二极管。  
Schottky Diode in a SOD-323 Plastic Package.

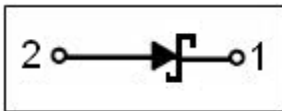
### 特征 / Features

符合 AEC-Q101 标准高可靠性要求，无卤产品。  
Qualified to AEC-Q101 Standards for High Reliability, HF Product.

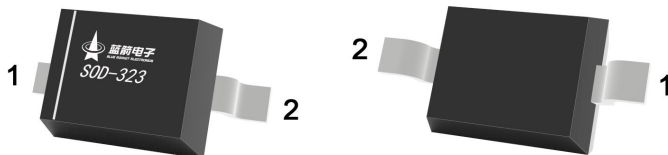
### 用途 / Applications

用于小信号处理，满足汽车应用的严格要求。  
Small signal diode, Meet the stringent requirements of automotive applications.

### 内部等效电路 / Equivalent Circuit



### 引脚排列 / Pinning



PIN1:Cathode

PIN2:Anode

### 印章代码 / Marking

Marking	Q86
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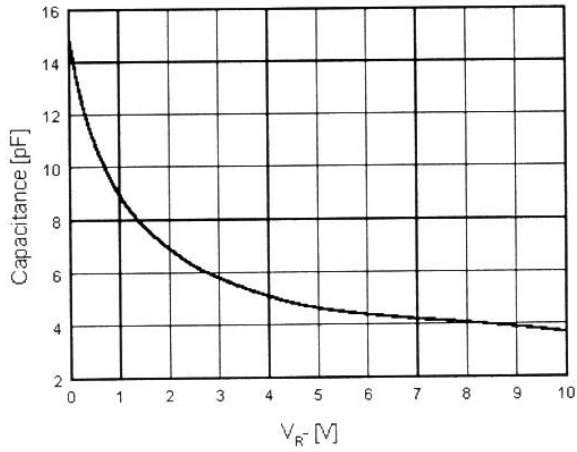
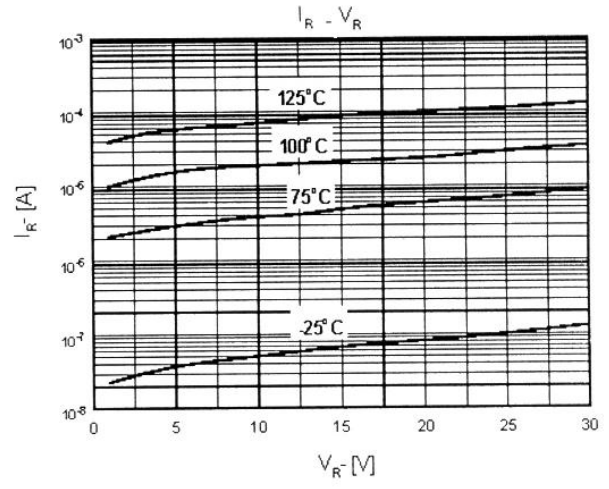
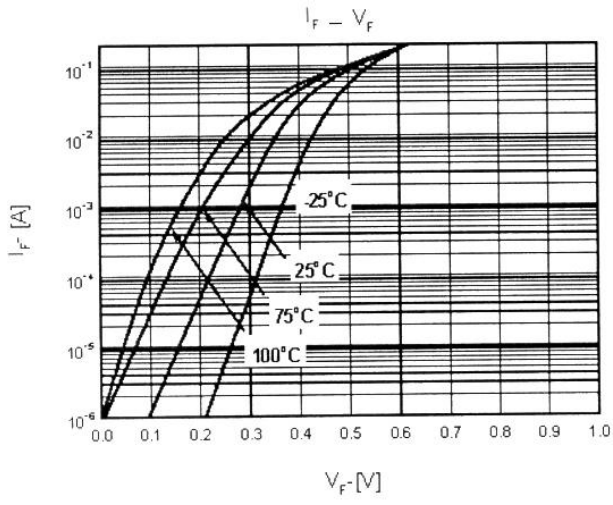
**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Continuous forward current	$I_F$	200	mA
Surge non repetitive forward current	$I_{FSM}$	600	mA
Power Dissipation	$P_D$	250	mW
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	430	°C/W
Junction Temperature Range	$T_J$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

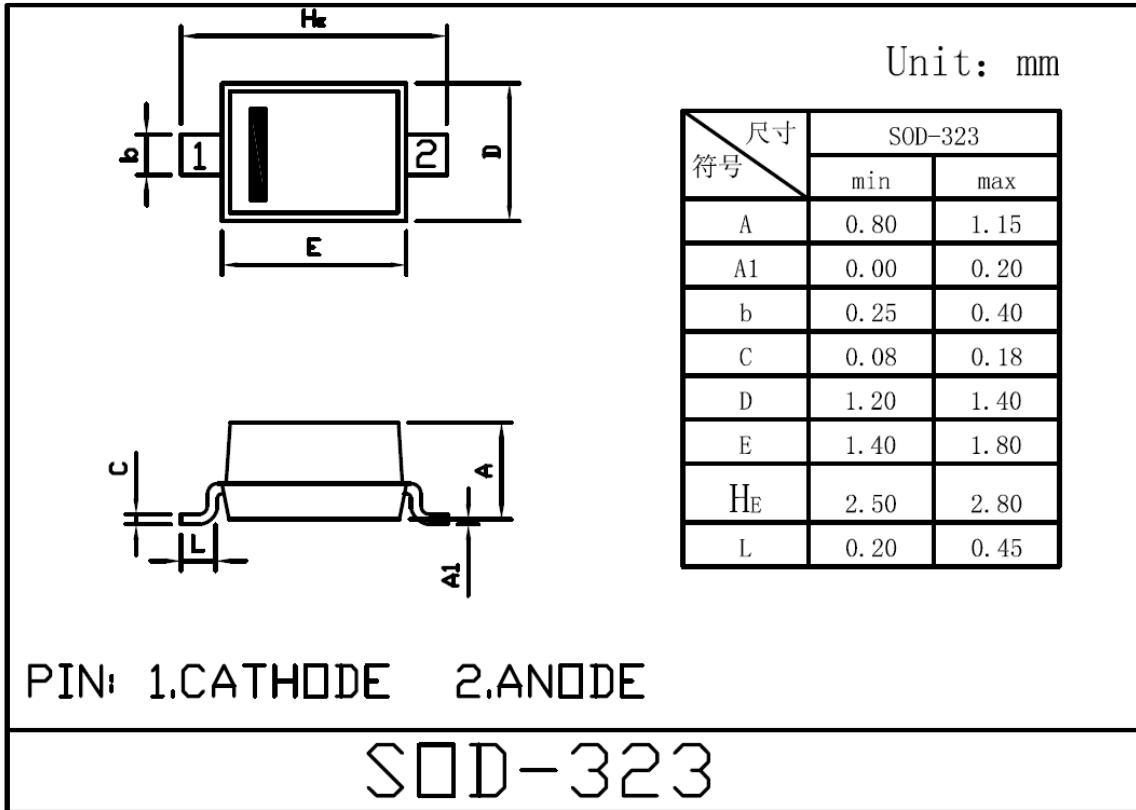
**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating		单位 Unit
			MIN	MAX	
Reverse Voltage	$V_R$	$I_R=10\mu A$	30		V
Peak Forward voltage	$V_F$	$I_F=0.1mA$		240	mV
		$I_F=1.0mA$		320	mV
		$I_F=10mA$		400	mV
		$I_F=30mA$		500	mV
		$I_F=100mA$		0.8	V
Instantaneous Reverse Current	$I_R$	$V_R=25V$		2.0	$\mu A$
Total capacitance	$C_T$	$V_R=1.0V$ $f=1.0MHz$		10	pF
Reverse recovery time	$t_{rr}$	$I_{RR}=1.0mA$ $R_L=100\Omega$ $I_F=10mA$		5.0	ns

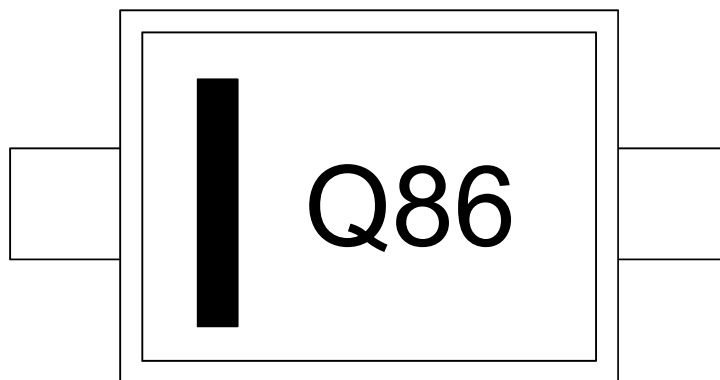
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



说明：

Q： 为汽车无卤产品标识

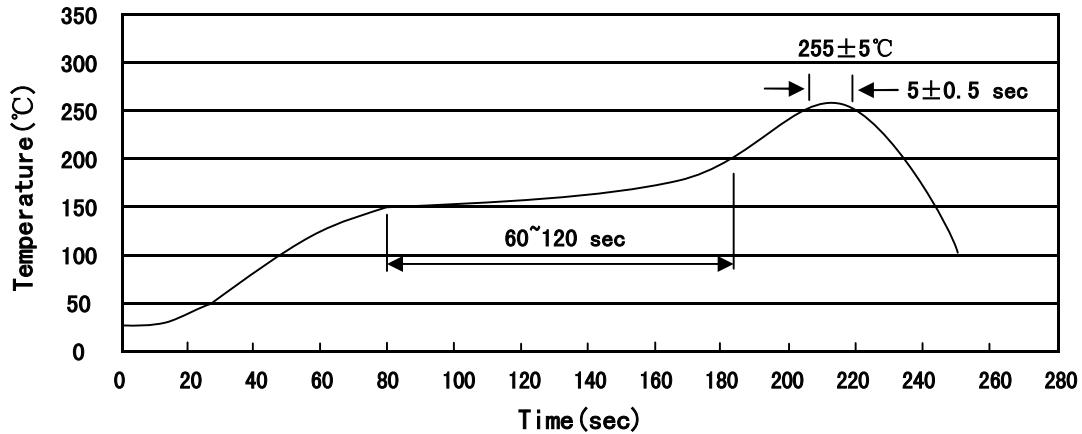
86： 为型号代码

Note:

Q: Automobile halogen-free product Code

86: Product Type

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度  $150 \sim 200^\circ\text{C}$ ，时间  $60 \sim 120\text{sec}$ ;
- 2、峰值温度  $255 \pm 5^\circ\text{C}$ ，时间持续为  $5 \pm 0.5\text{sec}$ ;
- 3、焊接制程冷却速度为  $2 \sim 10^\circ\text{C}/\text{sec}$ .

Note:

- 1.Preheating: $150 \sim 200^\circ\text{C}$ , Time: $60 \sim 120\text{sec}$ .
- 2.Peak Temp.: $255 \pm 5^\circ\text{C}$ , Duration: $5 \pm 0.5\text{sec}$ .
3. Cooling Speed:  $2 \sim 10^\circ\text{C}/\text{sec}$ .

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度： $260 \pm 5^\circ\text{C}$

时间： $10 \pm 1$  sec.

Temp.: $260 \pm 5^\circ\text{C}$

Time: $10 \pm 1$  sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323	3,000	10	30,000	6	180,000	7" × 8	180×120×180	390×385×205

**使用说明 / Notices**